SHORT BIO

Dr. Jaesik Lee is Vice President of Package Engineering at SK hynix America. In this role, Jaesik is responsible for the research and development of advanced packaging for next generation High Bandwidth Memory (HBM) and pathfinding initiatives which enrich SK hynix’s innovations. He also focuses on the collaborations with customers to overcome HBM challenges associated with System in Packages (SIPs).

Prior to joining SK hynix America, Jaesik has held various key technical positions through Meta, Google, Nvidia, and Qualcomm where he drove advanced packaging technology developments, Packaging and System Co-optimization, and Manufacturing in Mobile, AI, and HPC applications. He received a PhD in mechanical engineering from University of Waterloo.